PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5633037

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yu-Ting Chung	07/23/2019
Shawn Min	07/23/2019
Yi-Chun Hsieh	07/23/2019

RECEIVING PARTY DATA

Name:	Realtek Semiconductor Corp.	
Street Address:	2 Innovation Rd. II, Science Park	
City:	HsinChu	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16520317

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU

Address Line 1: 5F., NO.389, FUHE RD., YONGHE DIST.,

Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	REAP0981USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	07/23/2019

Total Attachments: 6

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: AMPLIFIER CIRCUIT

As the below named inventor, I heret This declaration is directed to:	y declare that:			
☑ The attached application, or				
☐ United States application number		filed on	, or	
☐ PCT international application number		filed on		
The above-identified application was	made or authorized to be made	by me.		
I believe that I am the original invento application.	or or an original joint inventor of	a claimed invention in	the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement made in this de sonment of not more than five (claration is punishable 5) years, or both.	e	
In consideration of the payment by	Realtek Semiconductor C	orp. having a po	stal address of	
2 Innovation Rd. II, Science Pa	ark, HsinChu 30076, Taiwa	n, R.O.C.		
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good and	I of the sum of One Dollar (\$ 1. d valuable consideration.	00), the receipt of whi	ch is hereby	
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applicat invention by the above application or substitutes, or extensions thereof, an	d to any and all improvements vi ion and, in and to, all Letters Pa any continuations, continuation	vhich are disclosed in itent to be obtained for in-part, divisions, rend	the r said ewals.	
I hereby covenant that no assignmen entered into which would conflict with	t, sale, agreement or encumbra this assignment;	nce has been or will b	e made or	
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, in maintain, issue and enforce said appi equivalents thereof which may be ned IN WITNESS WHEREOF, I have her	lication, said invention and said cessary or desirable to carry out	Letters Patent and sa the proposes thereof	id	
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire nventive entity, must accompany this form. Use this form for <u>each additional inventor.</u>				

Page 1 of 6

NPO#REA-P0981-USA:0 CUST#107A-248US

Docket No REAP0981USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yu-Ting Chung

Date:

JUL 2 3 2019

Signature: Yu-Ting Chung

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F#NPO-P0002E-US1201 DSB0-108U003248

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: AMPLIFIER CIRCUIT

As the below named inventor, I here This declaration is directed to:	eby declare that:			
☑ The attached application, or				
. 🗖 United States application กเ	ımber	filed	on	, or
☐ PCT international applicatio	n number	file	ed on	
The above-identified application was	s made or authorized to	be made by me.	•	
I believe that I am the original inventable application.	tor or an original joint inv	entor of a claime	ed invention in	the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impi	ul false statement made risonment of not more th	in this declaratio an five (5) years	n is punishable , or both.	•
In consideration of the payment by	Realtek Semicond	uctor Corp.	having a pos	stal address of
2 Innovation Rd. II, Science P	ark, HsinChu 30076	, Taiwan, R.O	.C.	
(referred to as "ASSIGNEE"below) t acknowledged, andfor other good a	to I of the sum of One Do nd valuable consideratio	ollar (\$ 1.00), the n.	receipt of whice	ch is hereby
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified applica- invention by the above application of substitutes, or extensions thereof, a	and to any and all improv ation and, in and to, all L or any continuations, con	ements which ar etters Patent to t tinuation-in-part,	re disclosed in be obtained for divisions, rene	the said wa is .
I hereby covenant that no assignme entered into which would conflict wit	ent, sale, agreement or el th this assignment;	ncumbrance has	been or will be	e made or
I further covenant that ASSIGNEE wand documents relating to said inveknown and accessible to I and will trelated thereto and will promptly exe	ntion and said Letters Pa estify as to the same in a	atent and legal early interference.	quivalents as n litigation proce	nav be
representatives any and all papers, maintain, issue and enforce said ap equivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, said invention a ecessary or desirable to	and said Letters carry out the pro	Patent and sai	d .
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire nventive entity, must accompany this form. Use this form for each additional inventor.				

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NPO#REA-P0981-USA:0 CUST#107A-248US

Docket No REAP0981USA

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Shawn Min	Date:	JUL 2 3 2019	
Signature:	Shawn Min			_

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: AMPLIFIER CIRCUIT

As the below named inventor, I hereby declare that This declaration is directed to:	:	
☑ The attached application, or		
☐ United States application number	filed on	or
☐ PCT international application number	filed on	
The above-identified application was made or author	orized to be made by me.	
I believe that I am the original inventor or an origina application.	Il joint inventor of a claimed invention in the	
I hereby acknowledge that any willful false statement under 18 U.S.C. 1001 by fine or imprisonment of not	nt made in this declaration is punishable t more than five (5) years, or both.	
In consideration of the payment by Realtek Sen	niconductor Corp. having a postal add	ress of
2 Innovation Rd. II, Science Park, HsinChu	u 30076, Taiwan, R.O.C.	
(referred to as "ASSIGNEE"below) to I of the sum o acknowledged, andfor other good and valuable con	f One Dollar (\$ 1.00), the receipt of which is hel sideration.	eby
I hereby sell, assign and transfer to ASSIGNEE and the entire right, title and interest in and to any and a invention as above-identified application and, in and invention by the above application or any continuati substitutes, or extensions thereof, and as to Letters	Ill improvements which are disclosed in the disclosed in the discount to be obtained for said ons, continuation-in-part, divisions, renewals.	EE
I hereby covenant that no assignment, sale, agreementered into which would conflict with this assignment	nent or encumbrance has been or will be made ent;	or
I further covenant that ASSIGNEE will, upon its requent and documents relating to said invention and said Landwill testify as to the seriated thereto and will promptly execute and delive	etters Patent and legal equivalents as may be same in any interference, litigation proceeding	ts
representatives any and all papers, instruments or a maintain, issue and enforce said application, said in equivalents thereof which may be necessary or des IN WITNESS WHEREOF, I have hereunto set hand	vention and said Letters Patent and said irable to carry out the proposes thereof.	
Note: An application data sheet (PTO/SB/14 or equinocutive entity, must accompany this form. Use this		

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NPO#REA-P0981-USA:0 CUST#107A-248US

Docket No REAP0981USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Yi-Chun Hsieh

Date:

JUL 2 3 2019

Signature:

I-Mun MSIO

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F#NPO-P0002E-US1201 DSB0-108U003248